

New jettable

conductive adhesives

for PCB assembly

from Panacol





Panacol presents new die-attach adhesives with improved conductivity. Jet dispense compatibility and snap cure speeds make these conductive adhesives the ideal choice for high speed production.

Panacol continues to expand its Elecolit®-product portfolio. Thanks to new, innovative filling materials and optimized hardener systems, die-attach adhesives with improved conductivity are now available. For maximum processing speed, these adhesives can be applied by jetting. New hardener systems in many of the one part epoxy based adhesives develop cure within minutes.

The new Elecolit® products are available in a range of viscosities to accommodate various applications and requirements. As conductivity is strongly dependent on the content of conductive filler, Panacol uses uniquely shaped filling materials to achieve an optimal fill ratio. This ensures high conductivity and consistent product performance.

Elecolit® 3661 is one of Panacol's high performance conductive adhesives formulated specifically for high volume die attach processes. It's small particle size silver filler permits fast, precise dispensing and delivers high post-cure conductivity.

- Click here for technical datasheet of Elecolit® 3661
- More information on our electrically conductive adhesives

